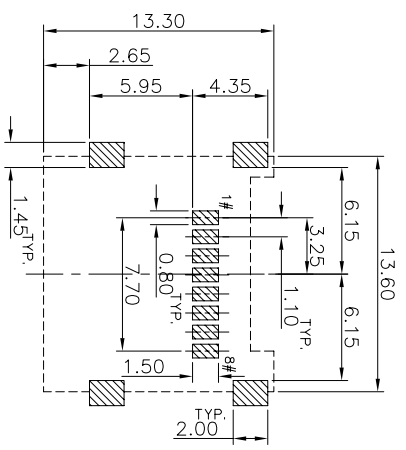


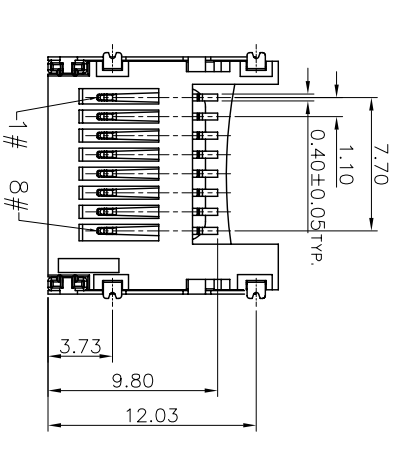
NOTES:

1. MATERIAL : HOUSING:HIGH TEMPERATURE THERMOPLASTIC. UL94V-0.BLACK
SHELL:STAINLESS STEEL.
LOCK:STAINLESS STEEL.
CONTACT:COPPER ALLOY.
DETECT PIN: COPPER ALLOY.
2. PLATING:
CONTACT: 20u" Min. Au PLATING IN CONTACT AREA;
100u" Min. Sn PLEATED OVERALL,
50u" Min. Ni UNDERPLATED OVERALL.

3. ELECTRICAL CHARACTERISTIC:
PAD:100u" Min. Sn PLATING OVER ALL
50u" Min. Ni UNDERPLATED OVERALL .
CONNECT RESISTANCE:80 MILLIONMS/PIN Max.
INSULATION RESISTANCE:1000 MEGOHMS Min.
VOLTAGE WITHSTAND:500V AC for 1minute
4. DATE CODE: *****



RECOMMENDED PCB PATTERN LAYOUT
TOLERANCE: ±0.05



Pin No.	Name	Type	DESCRIPTION
1	DAT2	I/O/PP	Data Line [bit2]
2	CD/DAT3	I/O/PP	Card Detect Data Line [bit3]
3	CMD	PP	Command Response
4	VDD	S	Supply Voltage
5	CLK	I	Clock
6	VSS	S	Supply Voltage Ground
7	DAT0	I/O/PP	Data Line [bit0]
8	DAT1	I/O/PP	Data Line [bit1]

F	LOCK-L	1	SUS	/
E	LOCK-R	1	SUS	/
D	Shell	1	STAINLESS STEEL	/
C	Contact	8	COPPER ALLOY	Au 20u"
B	Housing	1	HIGH TEMP. THERMOPLASTIC	(UL94-V0).BLACK
A	PAD	4	COPPER ALLOY	Sr:100u" min Ni:50u" min

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
1	UNLESS OTHERWISE SPECIFIED TOLERANCES			
	DECIMALS:		ANGLES:	
	X :±0.5		X :±2	
	X.X :±0.3		X.X :±1	
	X.XX :±0.2			

TITLE	TRANS FLASH HIGNE TYPE W/LOCK
羅軍華 3/9/07	PART NO: 2CA-0007-B11
劉木遠 3/19/07	SCALE:N/A UNIT: mm
Seadn 3/19/07	SIZE: A4 SHEET: 10F1 REV: A



REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRELIMINARY	羅軍華	3/9/07